

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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High Performance Insulator for Low-Pressure Applications

Features and Benefits

- Thermal impedance:
 0.61°C-in²/W (@50 psi)
- · Electrically isolating
- · Low mounting pressures
- · Smooth and highly compliant surface
- General-purpose thermal interface material solution



The true workhorse of the Sil-Pad product family, Sil-Pad 900S thermally conductive insulation material, is designed for a wide variety of applications requiring high thermal performance and electrical isolation. These applications also typically have low mounting pressures for component clamping.

Sil-Pad 900S material combines a smooth and highly compliant surface characteristic with high thermal conductivity. These features optimize the thermal resistance properties at low pressures.

Applications requiring low component clamping forces include discrete semiconductors (TO-220,TO-247 and TO-218) mounted with spring clips. Spring clips assist with quick assembly and apply a limited amount of force to the semiconductor. The smooth surface texture of Sil-Pad 900S minimizes interfacial thermal resistance and maximizes thermal performance.

TYPICAL PROPERTIES OF SIL-PAD 900S						
PRO PERT Y	IMPERIAL VALUE		METRIC VALUE		TEST METHOD	
Color	Pink		Pink		Visual	
Reinforcement Carrier	Fiberglass		Fiberglass		_	
Thickness (inch) / (mm)	0.009		0.229		ASTM D374	
Hardness (Shore A)	92		92		ASTM D2240	
Elongation (%45° to W arp and Fill)	20		20		ASTM D412	
Tensile Strength (psi) / (MPa)	1300		9		ASTM D412	
Continuous Use Temp (°F) / (°C)	-76 to 356		-60 to 180		_	
ELECTRICAL						
Dielectric Breakdown Voltage (Vac)	5500		5500		ASTM D149	
Type 3 Electrodes	8300		8300		ASTM D149	
Dielectric Constant (1000 Hz)	6.0		6.0		ASTM D150	
Volume Resistivity (O hm-meter)	10 ¹⁰		10 ¹⁰		ASTM D257	
Flame Rating	V-O		V-O		U.L. 94	
THERMAL						
Thermal Conductivity (W /m-K)	1.6		1.6		ASTM D5470	
THERMAL PERFORMANCE vs PRESSURE						
Press	sure (psi)	10	25	50	100	200
TO -220 Thermal Performance (°C/W)		3.96	3.41	2.90	2.53	2.32
Thermal Impedance (°C-in²/W) (1)		0.95	0.75	0.61	0.47	0.41

¹⁾ The ASTM D5470 test fixture was used. The recorded value includes interfacial thermal resistance. These values are provided for reference only. Actual application performance is directly related to the surface roughness, flatness and pressure applied.

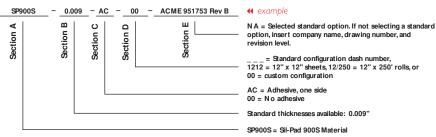
Typical Applications Include:

- · Power supplies
- · Automotive electronics
- · Motor controls
- · Power semiconductors

Configurations Available:

- · Sheet form, die-cut parts and roll form
- · W ith or without pressure sensitive adhesive

Building a Part Number



Note: To build a part number, visit our website at www.bergquistcompany.com.

Sil-Pad®: U.S. Patents 4,574,879; 4,602,125; 4,602,678; 4,685,987; 4,842,911 and others

Standard Options